# **Power MOSFET**

# 30 V, 14.7 A, N-Channel, SO-8 Leadless Package

#### **Features and Benefits**

- Fast Switching Performance
- Low t<sub>RR</sub> and Q<sub>RR</sub> Optimized for Synchronous Operation
- Low R<sub>DS</sub>(on) to Minimize Conduction Loss
- Optimized FOM (Q<sub>GD</sub> x R<sub>DS(on)</sub>)
- Low Gate Charge to Minimize Switching Losses

#### **Applications**

- Server and Notebook Power Supplies
- DC-DC Converters

# **MAXIMUM RATINGS** (T<sub>J</sub> = 25°C unless otherwise stated)

Pa	Symbol	Value	Unit			
Drain-to-Source Voltage			$V_{DSS}$	30	V	
Gate-to-Source Volta	age	_	$V_{GS}$	±20	V	
Continuous Drain	Steady State	T <sub>A</sub> = 25°C	I <sub>D</sub>	10	Α	
Current (Note 1)		T <sub>A</sub> = 85°C		7.2		
	t ≤ 10 s	T <sub>A</sub> = 25°C		14.7		
Power Dissipation			$P_{D}$	2.3	W	
(Note 1)	t ≤10 s			5.0		
		T <sub>A</sub> = 25°C	I <sub>D</sub>	7.0	Α	
Current (Note 2)		T <sub>A</sub> = 85°C		5.0		
Power Dissipation (Note 2)	Steady State	T <sub>A</sub> = 25°C	P <sub>D</sub>	1.13	W	
Pulsed Drain $t_p = 10 \mu s$ Current (Note 1)			I <sub>DM</sub>	30	Α	
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C	
Source Current (Body Diode)			I <sub>S</sub>	10	Α	
Lead Temperature for Soldering Purposes (1/8 in from case for 10 s)			TL	260	°C	

#### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	55	°C/W
Junction-to-Ambient – $t \le 10 \text{ s}$ (Note 1)	$R_{\theta JA}$	25	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	110	°C/W

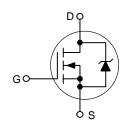
- Surface-mounted on FR4 board using 1 sq. in. pad size (Cu. area = 1.127 sq. in. [1 oz] including traces).
- 2. Surface–mounted on FR4 board using minimum recommended pad size (Cu. area = 0.0821 sq. in.).



# ON Semiconductor®

## http://onsemi.com

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> TYP	I <sub>D</sub> MAX	
30 V	11.8 mΩ @ 10 V	14.7 A	
30 V	15 mΩ @ 4.5 V	14.7 A	





SO-8 Leadless CASE 751AD

## MARKING DIAGRAM



XXXX = Specific Device Code A = Assembly Location

Y = Year WW = Work Week

# **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NTLMS4501NR2	SO-8 Leadless	2500/Tape & Reel

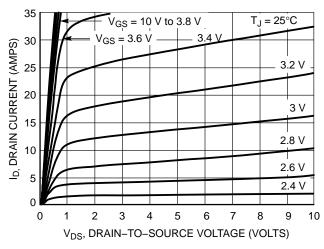
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		30	33		V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V(BR)DSS/TJ				25		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 24 V	T <sub>A</sub> = 25°C			0.8	μΑ
		$V_{DS} = 24 \text{ V}$	T <sub>A</sub> = 125°C			10	
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{DS} = 0 V, V_{GS} =$	= ±20 V			±100	nA
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>		050 . 4	1.0	1.7	2.0	V
Negative Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>	$V_{GS} = V_{DS}, I_D =$	250 μΑ		-4.0		mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> =	: 14.7 A		11.8	13.5	mΩ
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub>	= 13 A		15	16.5	1
Forward Transconductance	9FS	V <sub>DS</sub> = 10 V, I <sub>D</sub> =	: 14.7 A		20		S
CHARGES AND CAPACITANCES							
Input Capacitance	C <sub>ISS</sub>				1010	1100	pF
Output Capacitance	Coss	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 20 V			325		1
Reverse Transfer Capacitance	C <sub>RSS</sub>				94		1
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS} = 4.5 \text{ V}, V_{DS} = 10 \text{ V},$ $I_D = 14.7 \text{ A}$			9.25	9.7	nC
Gate-to-Source Gate Charge	$Q_{GS}$				3.2		1
Gate-to-Drain "Miller" Charge	$Q_{GD}$				3.6		1
SWITCHING CHARACTERISTICS (Note 4)							
Turn-On Delay Time	t <sub>d(ON)</sub>				8.5	9.5	ns
Rise Time	t <sub>r</sub>	$V_{GS}$ = 10 V, $V_{DS}$ = 15 V, $I_{D}$ = 14.7 A, $R_{G}$ = 2.5 $\Omega$			37	39	1
Turn-Off Delay Time	t <sub>d(OFF)</sub>				22	25	1
Fall Time	t <sub>f</sub>				6.0	8.0	1
DRAIN-SOURCE DIODE CHARACTERISTIC	<b>S</b> (Note 3)		•				
Forward Diode Voltage	$V_{SD}$	V 0V 1 40 A	T <sub>A</sub> = 25°C		1.0	1.2	V
		$V_{GS} = 0 \text{ V}, I_{S} = 10 \text{ A}$ $T_{A} = 25^{\circ}\text{C}$ $T_{A} = 125^{\circ}\text{C}$			0.8		1
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS} = 0 \text{ V, } dI_{S}/dt = 100 \text{ A/}\mu\text{s,}$ $I_{S} = 10 \text{ A}$			29	35	ns
Charge Time	ta				15		1
Discharge Time	t <sub>b</sub>				18		1
Reverse Recovery Charge	Q <sub>RR</sub>				0.022		nC

Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

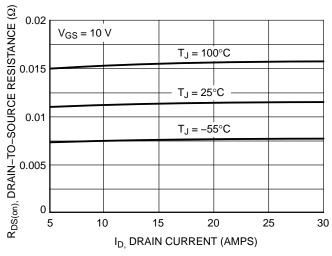
# TYPICAL PERFORMANCE CURVES (T<sub>J</sub> = 25°C unless otherwise noted)



 $V_{DS} \ge 10 \text{ V}$   $V_{D$ 

Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



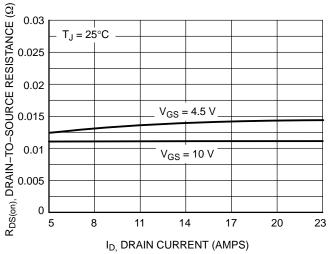
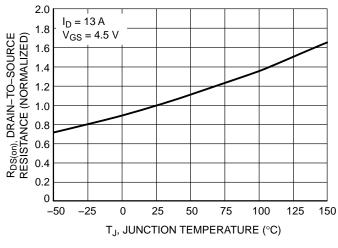


Figure 3. On–Resistance vs. Drain Current and Temperature

Figure 4. On–Resistance vs. Drain Current and Gate Voltage



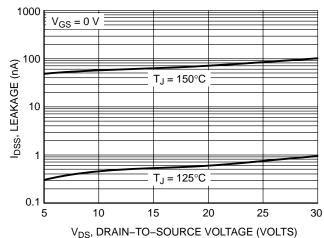


Figure 5. On–Resistance Variation with Temperature

Figure 6. Drain-to-Source Leakage Current vs. Voltage

# TYPICAL PERFORMANCE CURVES (T<sub>J</sub> = 25°C unless otherwise noted)

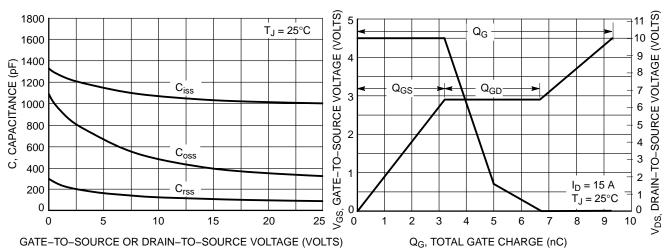


Figure 7. Capacitance Variation

Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

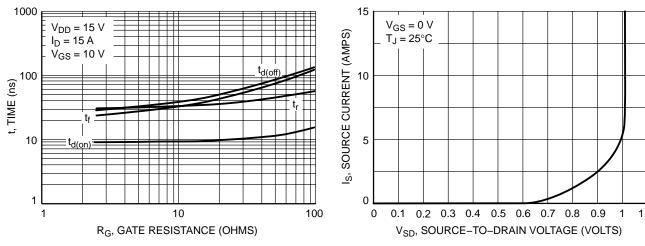


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

Figure 10. Diode Forward Voltage vs. Current

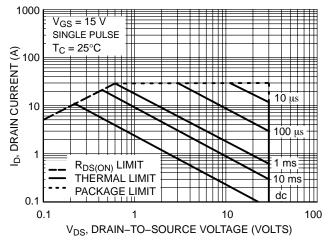
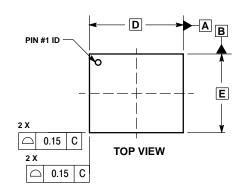
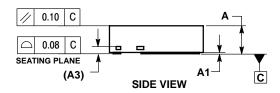


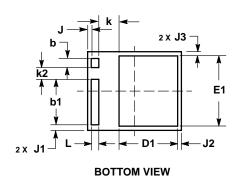
Figure 11. Maximum Rated Forward Biased Safe Operating Area

# **PACKAGE DIMENSIONS**

SO-8 Leadless CASE 751AD-01 ISSUE O







- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION:

MΙ	LL	IΜ	F٦	ΓF	R

	MILLIMETERS		
DIM	MIN	MAX	
Α	1.750	1.950	
A1	0.000	0.050	
A3	0.254	REF	
b	0.400	0.600	
b1	2.930	3.030	
D	6.200 BSC		
D1	3.777	3.977	
E	5.200 BSC		
E1	4.544	4.744	
J	0.027	0.227	
J1	0.350	0.550	
J2	0.154	0.354	
J3	0.178	0.378	
k	1.246	1.446	
k2	0.680	0.880	
L	0.500	0.700	

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